

# SPECIFICATION

SPEC TO : \_\_\_\_\_

DESCRIPTION : 1-2W LED

DATE : 2012/12/26

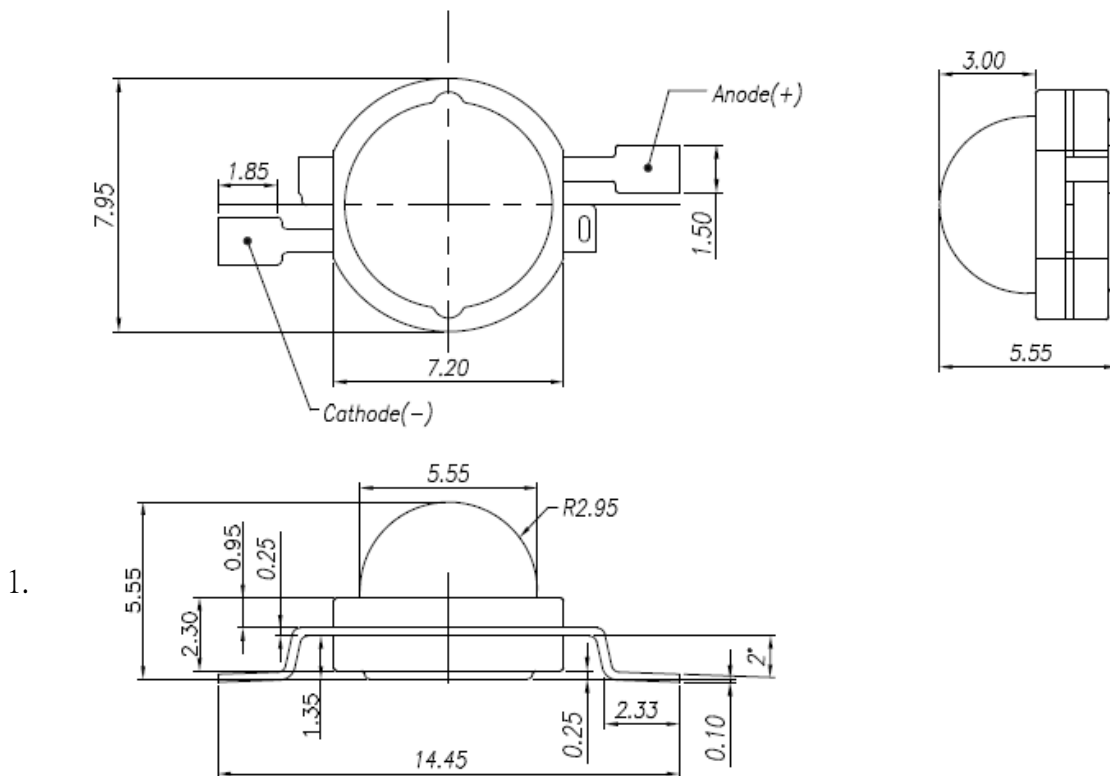
## ■ Feature

- ◆ 1W High Power Emitter LED
- ◆ Silicone compression molding lens
- ◆ Half Angle ( $2\theta$  1/2) :  $120^\circ$
- ◆ Lens Color : Silicon Water Clear

## ■ Applications

- ◆ General Lighting
- ◆ Decorative lighting
- ◆ Architectural Lighting
- ◆ Street Lamps

## ■ Package Dimensions



Notes :  
All

dimensions are in millimeters

2. Tolerance is  $\pm 0.25$  unless otherwise noted

Part NO.	LED Chip		LED Emitted Color	Lens Color	Description
	Material	Emitted Color			
	InGaN	Blue	White	Clear	Silicon Water Clear

## ■ Electrical/Optical Characteristics (At TA=25°C)

Parameter	Symbol	Conditions	Min.	Avg.	Max.	Units
Luminous Flux	$\Phi_V$	IF=350mA	80		120	lm
Color Temperature	CCT	IF=350mA	2700		7500	K
Forward Voltage	$V_F$	IF=350mA	3.0	3.3	3.6	V
Thermal Resistance Junction To Board	$R_{thJ-B}$	IF=350mA		13		°C/W
Temperature Coefficient of Forward Voltage	$\Delta V_F/\Delta T$	IF=350mA		2		mV/°C
Reverse Current	IR	VR=5V			10	$\mu A$
Viewing Angle [1]	$2\theta_{1/2}$	IF=350mA		120		Deg
Color Render Index (CRI)	Ra	IF=350mA	60			

## ■ Absolute Maximum Rating(At TA=25°C) (极限参数)

Parameter	Symbol	Ratings	Units
Power Dissipation	$P_D$	1.4	W
Continuous Forward Current	$I_F$	350	mA
Peak Forward Current [2]	$I_F(\text{Peak})$	700	mA
LED Junction Temperature	$T_J$	120	°C
Reverse Voltage	$V_R$	5	V
Operating Temperature Range	$T_{OPR}$	-30°C To +80°C	
Storage Temperature Range	$T_{STG}$	-40°C To +100°C	
Manual Soldering Temperature	$T_{SOL}$	260°C±20°C For 3-5 Seconds	
ESD Sensitivity	ESD	2000V HBM	

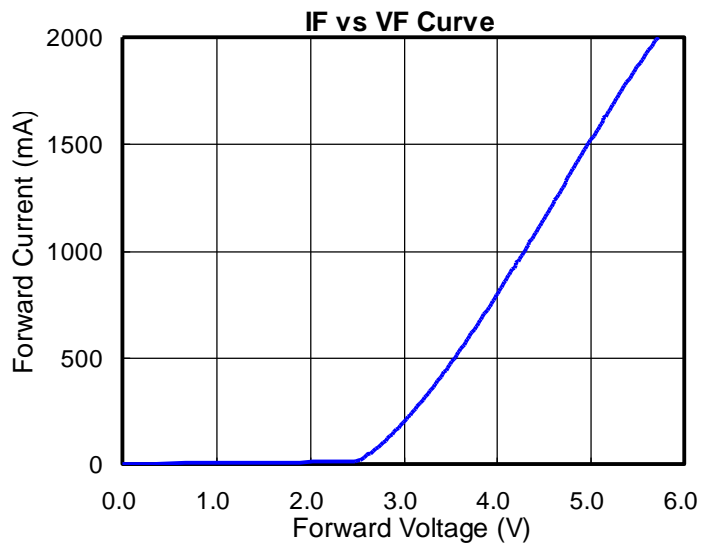
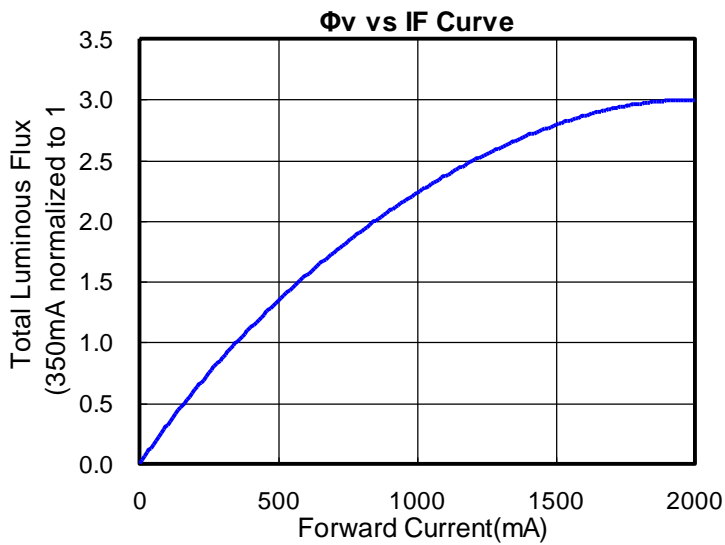
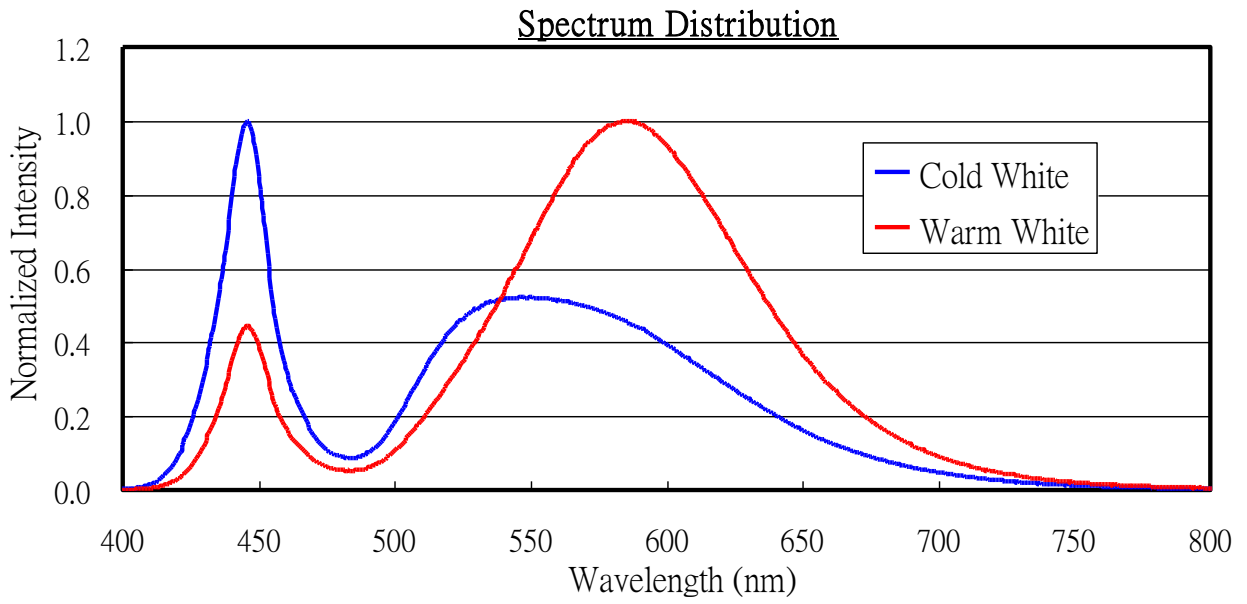
### Notes:

[1]. Tolerance  $\Theta$ :10% ,

[2]. 1/10 Duty Cycle 0.1ms Pulse Width.

## ■ Spectrum Distribution

■  
Ch  
ara  
cte  
rist  
ics  
Cu  
rve



## Notice

1. In order to avoid absorption of moisture, it is recommended that the products are stored in the dry box (or desiccators ) with a desiccants. Alternatively the following environment is recommended:  
Storage temperature : 5°C~30°C Humidity:60% HR max.
2. If the storage conditions are of high humidity the product should be dried before use.  
Recommended drying conditions: 12 hours at 100°C±5°C
3. Any mechanical force or any excess vibration should be avoid during the cooling process after soldering.
4. Reflow rapidly cooling should be avoided.
5. Components should not be mounted on distorted Printed Circuit Boards.
6. Devices should not contact with any types of fluid, such as water , oil , organic solvents··· etc.
7. The maximum ambient temperature should be taken into consideration when determining the operating current.
8. Devices should be soldered within 7 days after opening the moisture-proof packing.
9. Repack unused product in anti-moisture packing, fold to close any opening and store in a dry place.
10. The appearance and specifications of devices may be modified for improvement without notice.
11. ESD Precautions Static Electricity and surge damages LEDs. It is recommended that wrist bands or anti-electrostatic gloves be used when handing the LEDs . All devices, equipment and machinery should be properly grounded.
12. This product must be driven by constant power supplier.